2022 IEEE R10 EXCOM Virtual Meeting
Date: 7 January 2023

2023 R10 Industry Relations Committee Plan

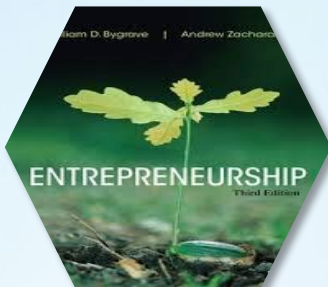*Name: Sanjay Kar Chowdhury*
2023 R10 IRC Committee Chair

Vision

Leadership in State-of-the-Art Technology and bridging industry & academia gap

Mission

By free & mutual exchange of Ideas between Industry & academia to foster Innovation, Internship & Entrepreneurship

2022 R10 Industry Relations Committee Plan

Committee Structure
1. Chair: Sanjay Kar Chowdhury
2. Members: Dr. H.L. Bajaj, Ms. Agnes Irwanti, Haruhiko Okumura, John Jose, Sambit Bakshi, Leith Campbell.

Objectives
1. Strengthening Industry Academia Interactions through Workshops.
2. Leadership in State-of-the-Art-Technology through webinars(R10TALK), Organising Industry forum at TENCON, TENSYMP & HTC.
3. Recruitment of New members from Industry

Projects / Tasks
Project 1: Organizing Workshops on Industry Academia Engagement through TISP.
Project 2: Organizing Webinar (R10TALK) on contemporary topics. Workshops, seminars, panel discussions during TENCON, TENSYMP & HTC.
Project 3: R10 Industry Conclave during HTC-2023

Budget
Project 1: Support to different OU s for conducting Workshops through TISP $ 5,000
Project 2: Guest Speakers for TENCON + TENSYMP + HTC: NIL (Speakers to be sourced locally)

Project 3: R10 Industry Conclave : $ 10,000

Total Proposed Budget in USD: 15,000

Project / Task Measurable
Project 1: Number of participants from Industry & New Members recruited from Industry
Project 2: Number of Programmes & New Members recruited.
Project 3: Number of Participating Corporate Houses & new members from industry

Major Milestones & Timeline
Project 1: From March to October 2023
Project 2: R10TALK: every month of the calendar year from March 2023 - 2 webinars per month. TENSYMP (Canberra), TENCON (Bangkok), HTC(Gujarat)
Project 3: Industry Conclave (during HTC 2023)

Details of Project 1

Workshops on Industry Academia Engagement:

Industry Academia Engagement:

Activity:
One Workshop to be organized by each selected Sections & Sub-Sections. Ten such OUs to be selected & funded on merit basis.

FDP / TISP to be organized aligned with Industry 4.0 applications like IT/ OT, IoT, Blockchain, Big Data etc.
To include hands on training and real life applications. Faculties for conducting workshops to be drawn from practising Engineers.

Notification for RFP   : 10/03/2023
RFP Closure Date   : 09/04/2023
Acceptance Notification : 20/04/2023
Programme Roll-out Date : 01/06/2023
Programme Closure Date : 31/10/2023
Max program to be accepted: 10
Collaborators: YP,WIE groups of Sections.
Budget: $ 500 x 10 = **$ 5000**

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Details of Project 2

Leadership in State-of-the-Art Technology:

R10TALK Webinar: On contemporary topics on Engineering & Professional fields in collaboration with PA, SAC, YP & WIE committees.

Industry Forums at R10 Flagship Conferences:

Establishing Industry forum during-

a) TENSYMP-2023 at Canberra (Sept'23)

b) HTC-2023 at Rajkot, Gujarat (Oct'23)

c) TENCON-2023 at Bangkok (Nov'23)

Details:

To start from March 2023.
At least 1 webinar per month till November'23
To collaborate with PES for webinar session in April'23 to coincide with PES day.
Budget: Nil

Travel support & Felicitations to Guest Speakers NIL for each conferences.

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Details of Project 3

R10 Industry Conclave:

Theme: Industry 4.0

A two day event to be hosted by Gujarat Section in conjunction with HTC-2023
The event shall have the following programme structure:

Day-1:
Inauguration and following events:

Day-1&2
Technology Leadership Forum:
Speakers to be drawn from leading industry houses both local & international

Student & YP Forum:
Panel Discussion on Contemporary topics where Students & YP shall interact with the industry captains.

Technology Exhibition:
Stalls to be put up by Industries to display their innovations, practices and products

Paper Presentation on Innovative Practices by Industry on the following 3 tracks:
- Power & Energy
- Electronics, Communication & Instrumentation
- Computer Science & Computation

Best Paper in each track to be awarded.

Innovation & Knowledge Management Forum:
Industry Leaders to share the innovative practices being adopted recently thorugh Panel Discussions

Total Budget: $10,000

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